CRMGGH0804A

N-Channel 80V, 3.9mΩ Typ. Power MOSFET

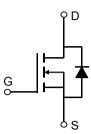
Description

Features

• 80V, 125A

 $R_{DS(ON)}$ Typ = 3.9m Ω @ V_{GS} = 10V Advanced Split Gate Trench Technology

- Excellent R_{DS(ON)} and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔVds TESTED!

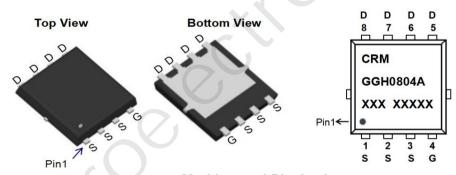




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Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMGGH0804A	CRMGGH0804A	PDFN5x6-8L	TAPING	13"	5000	60000

Absolute Maximum Ratings (@ T_J = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DS}	Drain-to-Source Voltage		80	V
V _{GS}	Gate-to-Source Voltage		±20	V
	Continuous Drain Current	T _C = 25°C	125	А
I _D		T _C = 100°C	75	А
I _{DM}	Pulsed Drain Current ⁽¹⁾		500	А
E _{AS}	Single Pulsed Avalanche Energy (2)		342	mJ
P_{D}	Power Dissipation	T _C = 25°C	132	W
$R_{ heta JC}$	Thermal Resistance, Junction to Case		0.95	°C/W
T_J,T_STG	Junction & Storage Temperature Range		-55 to 150	°C



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Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Chara	acteristics					
V _{(BR)DSS}	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	80	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 80V, V_{GS} = 0V$	-	-	1.0	μΑ
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Chara	acteristics				6	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2	3	4	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = 10V, I_D = 20A$	-	3.9	5.1	mΩ
Dynamic	Characteristics					
C _{iss}	Input Capacitance		- /	4850	-	pF
C_{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 40V,$ f = 1MHz	-	787	-	pF
C_{rss}	Reverse Transfer Capacitance	I - IIVINZ	X - \	16	-	pF
Q_g	Total Gate Charge		-	68	-	nC
Q_{gs}	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 40V, I_{D} = 20A$	<u> </u>	23	-	nC
Q_{gd}	Gate Drain("Miller") Charge	V _{DS} - 40 V, I _D - 20A	-	15	-	nC
Switchin	g Characteristics					
t _{d(on)}	Turn-On DelayTime		-	20	-	ns
t _r	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 40V$	-	38	-	ns
$t_{\text{d(off)}}$	Turn-Off DelayTime	I_D = 20A, R_{GEN} = 3Ω	-	30	-	ns
t_{f}	Turn-Off Fall Time		-	15	-	ns
Drain-So	urce Diode Characteristics and M	Max Ratings				
Is	Maximum Continuous Drain to Source Diode Forward Current		-	-	125	Α
I _{SM}	Maximum Pulsed Drain to Source Diode	Forward Current	-	-	500	Α
V_{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = 20A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	1 004 11/11 1004/	-	48	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F = 20A$, di/dt = 100A/us	-	100	-	nC

Notes:

^{1.} Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

^{2.} E_{AS} condition: Starting T_J =25°C, V_{DD} =40V, V_G =10V, R_G =25ohm, L=0.5mH, I_{AS} =37A

^{3.} Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%.

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Test Circuit

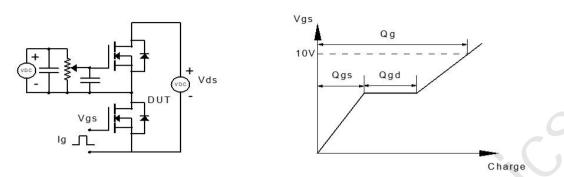


Figure 1: Gate Charge Test Circuit & Waveform

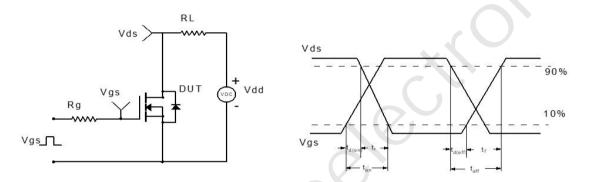


Figure 2: Resistive Switching Test Circuit & Waveform

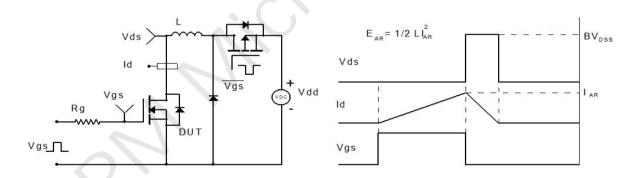


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

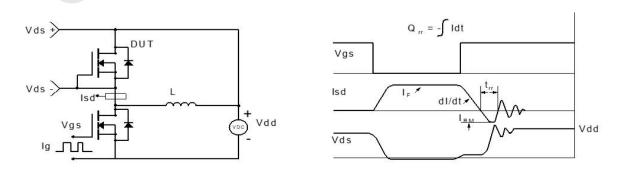
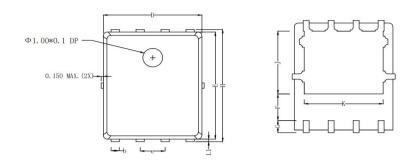


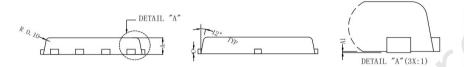
Figure 4: Diode Recovery Test Circuit & Waveform

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Package Mechanical Data(PDFN5x6-8L)





Dimensions In Millimeterer				
Symbol Symbol	MIN	TYP	MAX	
A	0.90	1.00	1.10	
A1	0.00	0.03	0.05	
b	0. 25	0.30	0.35	
С	0. 254 REF			
D	4.80	4.90	5.00	
F	1.35 REF			
Е	5. 65	5. 75	5.85	
е	1. 27 BSC			
Н	5. 90	6.00	6.10	
L1	0.10	0.13	0.16	
G	0.55 REF			
K	4.00 REF			
J	3.45 REF			

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